

# MMDL914T1G, SMMDL914T1G, MMDL914T3G

## High-Speed Switching Diode

### Features

- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	$V_R$	100	V
Forward Current	$I_F$	200	mA
Peak Forward Surge Current	$I_{FM(surge)}$	500	mA
Non-Repetitive Peak Forward Current $t = 1.0 \mu s$ $t = 1.0 s$	$I_{FM}$	4.0 2.0	A

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board $T_A = 25^\circ C$ (Note 1) Derate above $25^\circ C$	$P_D$	200 1.57	mW mW/ $^\circ C$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	635	$^\circ C/W$
Junction and Storage Temperature	$T_J, T_{stg}$	-55 to 150	$^\circ C$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-4 Minimum Pad.

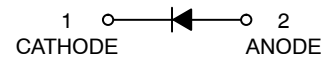


ON Semiconductor®

<http://onsemi.com>



SOD-323  
CASE 477  
STYLE 1



### MARKING DIAGRAM



5D = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MMDL914T1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel
SMMDL914T1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel
MMDL914T3G	SOD-323 (Pb-Free)	10,000 / Tape & Reel

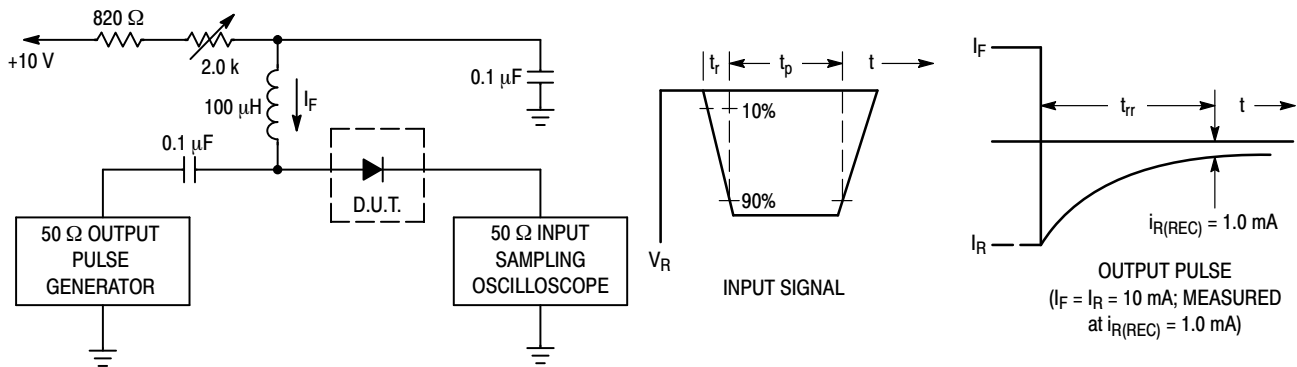
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MMDL914T1G, SMMDL914T1G, MMDL914T3G

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Reverse Breakdown Voltage ( $I_R = 100 \mu\text{A}$ )	$V_{(BR)}$	100	-	Vdc
Reverse Voltage Leakage Current ( $V_R = 20 \text{ Vdc}$ ) ( $V_R = 75 \text{ Vdc}$ )	$I_R$	-	25 5.0	nAdc $\mu\text{A}$ dc
Diode Capacitance ( $V_R = 0 \text{ V}$ , $f = 1.0 \text{ MHz}$ )	$C_T$	-	4.0	pF
Forward Voltage ( $I_F = 10 \text{ mA}$ )	$V_F$	-	1.0	Vdc
Reverse Recovery Time ( $I_F = I_R = 10 \text{ mA}$ ) (Figure 1)	$t_{rr}$	-	4.0	ns



- Notes: 1. A 2.0 k $\Omega$  variable resistor adjusted for a Forward Current ( $I_F$ ) of 10 mA.  
 2. Input pulse is adjusted so  $I_{R(peak)}$  is equal to 10 mA.  
 3.  $t_p \gg t_{rr}$

**Figure 1. Recovery Time Equivalent Test Circuit**

# MMDL914T1G, SMMDL914T1G, MMDL914T3G

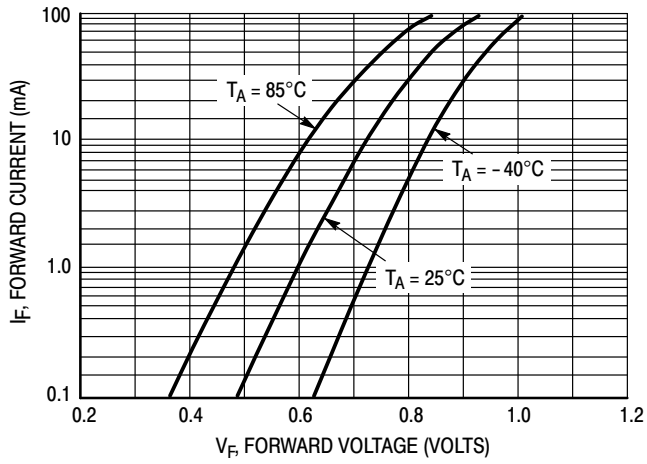


Figure 2. Forward Voltage

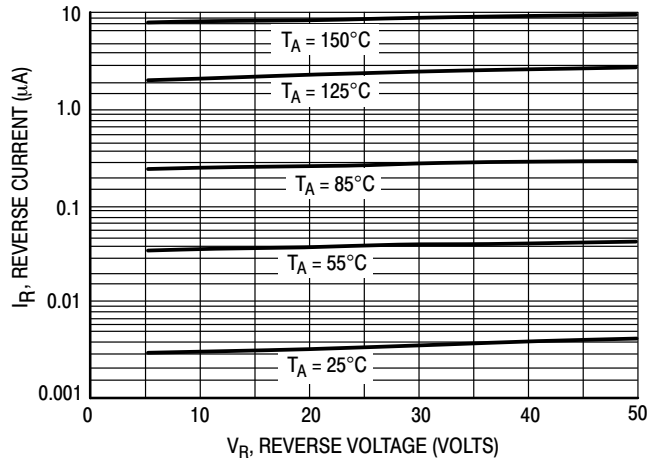


Figure 3. Leakage Current

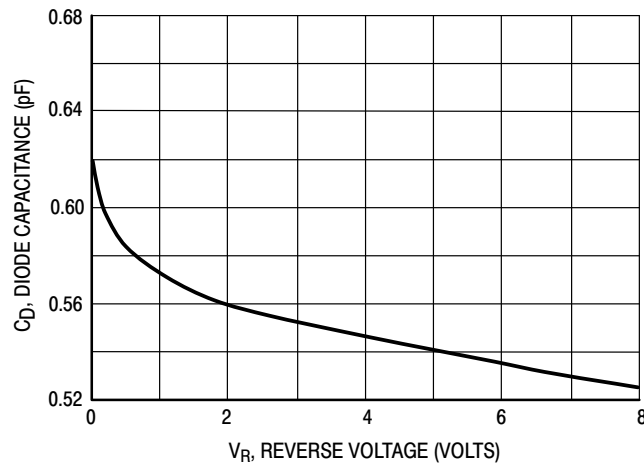
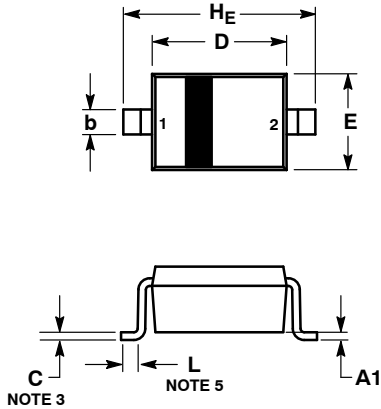


Figure 4. Capacitance

# MMDL914T1G, SMMDL914T1G, MMDL914T3G

## PACKAGE DIMENSIONS

SOD-323  
CASE 477-02  
ISSUE H



NOTES:

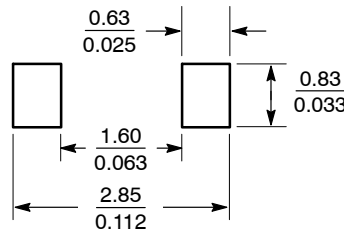
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
5. DIMENSION L IS MEASURED FROM END OF RADIUS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105

STYLE 1:

- PIN 1. CATHODE (POLARITY BAND)
- ANODE

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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